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PATENTS
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September 18, 2003

Mail Stop Patent Application
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

16934 U.S. PRO
 10/666399
 09/18/03

Re: MOLDED CHIP FABRICATION METHOD AND APPARATUS
 Docket No. P0298US-7

Sir:

Transmitted herewith for filing under 35 U.S.C. 111 and 37 CFR 1.53 is the patent application of MICHAEL S. LEUNG, ERIC TARSA and JAMES IBBETSON entitled MOLDED CHIP FABRICATION METHOD AND APPARATUS.

Enclosed are:

35 pages of written description, claims and abstract.
 11 sheets of drawings plus 2 copies.
 Declaration and Power of Attorney.

The filing and recording fees have been calculated as shown below:

Basic Fee				\$750.00	
Total Claims	(37- 20)	x	\$18.00	=	306.00
Independent Claims	(4- 3)	x	\$84.00	=	<u>84.00</u>
Total Fee:					\$1,140.00

Our Check No. 20639 for **\$1,140.00** to cover the filing and recording fees is enclosed. We authorize the Commissioner to charge (1) payment of any additional filing fees required under 37 CFR 1.16, (2) payment of any patent application processing fees under 37 CFR §1.17 associated with this communication, or (3) payment of any fees that occur during the pendency of this application (and to credit any overpayment) to Deposit Account No. 11-1580. We enclose a duplicate copy of this sheet.

Very truly yours,
 KOPPEL, JACOBS, PATRICK & HEYBL


 Jaye G. Heybl
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JGH/mm

Enclosures

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